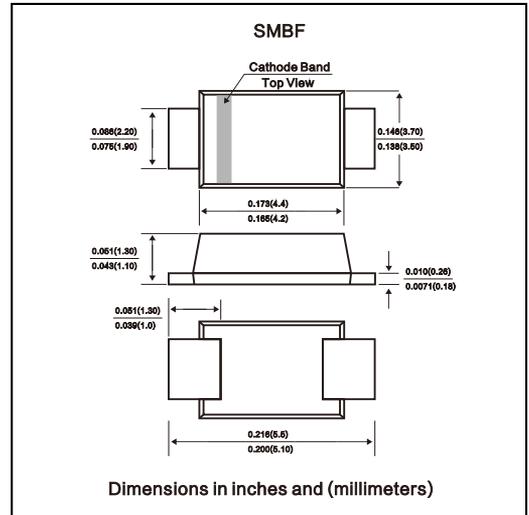


FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- Lead free in comply with EU RoHS 2011/65/EU directives

MECHANICAL DATA

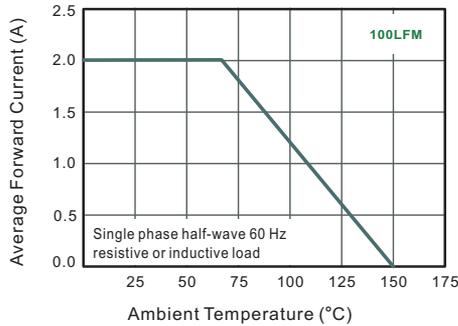
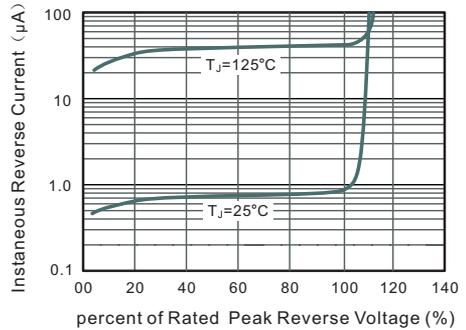
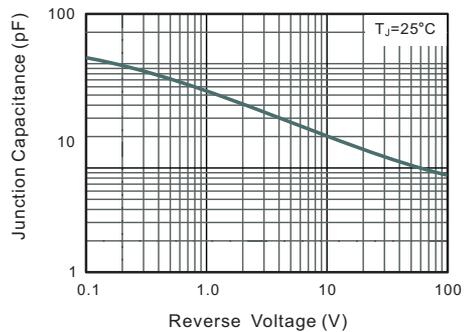
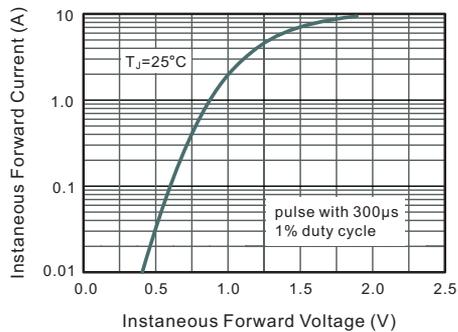
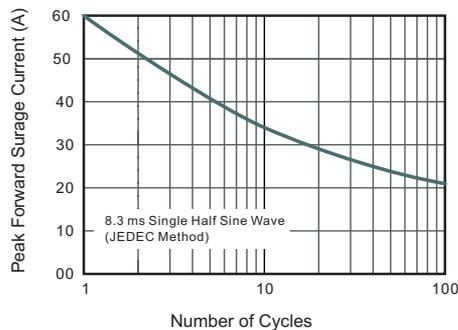
Case: JEDEC SMBF molded plastic body
Terminals: leads solderable per MIL-STD-750, Method 2026
Mounting Position: Any
Weight: 57mg/0.002oz


MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

MDD Catalog Number	SYMBOLS	GS2ABF	GS2BBF	GS2DBF	GS2GBF	GS2JBF	GS2KBF	GS2MBF	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at $T_L=65^\circ\text{C}$	$I_{(AV)}$	2.0							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	60							Amps
Maximum instantaneous forward voltage at 2.0A	V_F	1.1							Volts
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	5.0 100.0							μA
Typical junction capacitance (NOTE 1)	C_J	30							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	55							$^\circ\text{C/W}$
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +150							$^\circ\text{C}$

Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2. P.C.B. mounted with 0.5x0.5" (12.7x12.7mm) copper pad areas

Fig.1 Forward Current Derating Curve

Fig.2 Typical Reverse Characteristics

Fig.3 Typical Instaneous Forward Characteristics

Fig.6 Maximum Non-Repetitive Peak Forward Surge Current


The cruve graph is for reference only, can't be the basis for judgment!